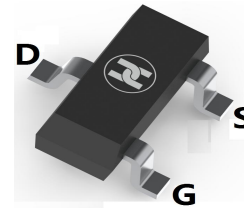
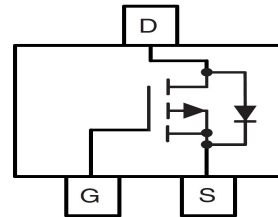


LOW VOLTAGE MOSFET (P-CHANNEL)

V_{DS}	-30	V
$V_{GS Max}$	± 20	V
$R_{DS(on) max}$ (@ $V_{GS} = -10V$)	64	mΩ
$R_{DS(on) max}$ (@ $V_{GS} = -4.5V$)	103	mΩ



SOT-23



Application(s)

- System/Load Switch

Features and Benefits

Features

Low $R_{DS(on)}$ ($\leq 64m\Omega$)
Industry-standard pinout
Compatible with existing Surface Mount Techniques
RoHS compliant containing no lead, no bromide and no halogen
MSL1, Consumer qualification

results in
⇒

Benefits

Lower switching losses
Multi-vendor compatibility
Easier manufacturing
Environmentally friendly
Increased reliability

Symbol	Parameter	Max.	Units
V_{DS}	Drain-Source Voltage	-30	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	-3.6	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	-2.9	
I_{DM}	Pulsed Drain Current	-15	
$P_D @ T_A = 25^\circ C$	Maximum Power Dissipation	1.3	W
$P_D @ T_A = 70^\circ C$	Maximum Power Dissipation	0.8	
	Linear Derating Factor	0.01	W/°C
V_{GS}	Gate-to-Source Voltage	± 20	V
T_J, T_{STG}	Junction and Storage Temperature Range	-55 to + 150	°C

Thermal Resistance


Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JA}$	Junction-to-Ambient ③	—	100	°C/W
$R_{\theta JA}$	Junction-to-Ambient ($t < 10s$) ④	—	99	

LOW VOLTAGE MOSFET (P-CHANNEL)

Electric Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	-30	—	—	V	$V_{GS} = 0V, I_D = -250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.02	—	V/ $^\circ\text{C}$	Reference to $25^\circ\text{C}, I_D = -1\text{mA}$
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	51	64	$\text{m}\Omega$	$V_{GS} = -10V, I_D = -3.6A$ ②
		—	82	103		$V_{GS} = -4.5V, I_D = -2.9A$ ②
$V_{GS(th)}$	Gate Threshold Voltage	1.2	—	2.4	V	$V_{DS} = V_{GS}, I_D = -10\mu A$
I_{DSS}	Drain-to-Source Leakage Current	—	—	1	μA	$V_{DS} = -24V, V_{GS} = 0V$
		—	—	150		$V_{DS} = -24V, V_{GS} = 0V, T_J = 125^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	-100	nA	$V_{GS} = -20V$
	Gate-to-Source Reverse Leakage	—	—	100		$V_{GS} = 20V$
R_G	Internal Gate Resistance	—	12	—	Ω	
g_{fs}	Forward Transconductance	3.5	—	—	S	$V_{DS} = -10V, I_D = -3.6A$
Q_g	Total Gate Charge	—	4.8	—	nC	$I_D = -3.6A$
Q_{gs}	Gate-to-Source Charge	—	1.2	—		$V_{DS} = -15V$
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	2.5	—		$V_{GS} = -4.5V$ ②
$t_{d(on)}$	Turn-On Delay Time	—	9.6	—	ns	$V_{DD} = -15V$ ②
t_r	Rise Time	—	19	—		$I_D = -1A$
$t_{d(off)}$	Turn-Off Delay Time	—	16	—		$R_G = 6.8\Omega$
t_f	Fall Time	—	15	—		$V_{GS} = -4.5V$
C_{iss}	Input Capacitance	—	388	—	pF	$V_{GS} = 0V$
C_{oss}	Output Capacitance	—	93	—		$V_{DS} = -25V$
C_{rss}	Reverse Transfer Capacitance	—	65	—		$f = 1.0\text{KHz}$

Source - Drain Ratings and Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	-1.3	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I_{SM}	Pulsed Source Current (Body Diode) ①	—	—	-15		
V_{SD}	Diode Forward Voltage	—	—	-1.2	V	$T_J = 25^\circ\text{C}, I_S = -1.3A, V_{GS} = 0V$ ②
t_{rr}	Reverse Recovery Time	—	14	21	ns	$T_J = 25^\circ\text{C}, V_R = -24V, I_F = -1.3A$
Q_{rr}	Reverse Recovery Charge	—	7.2	11	nC	$di/dt = 100A/\mu s$ ②

LOW VOLTAGE MOSFET (P-CHANNEL)

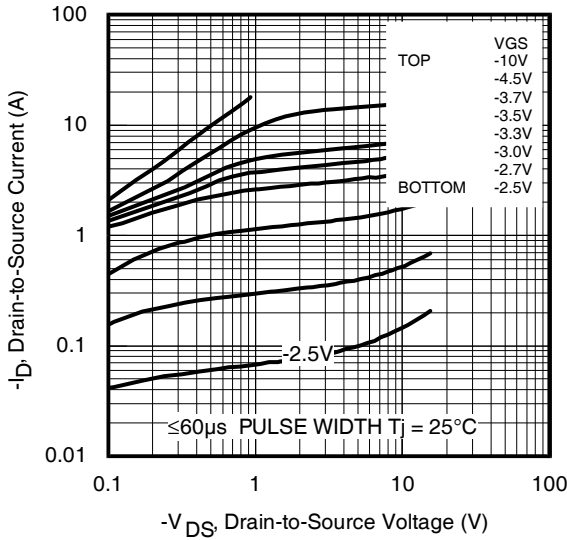


Fig 1. Typical Output Characteristics

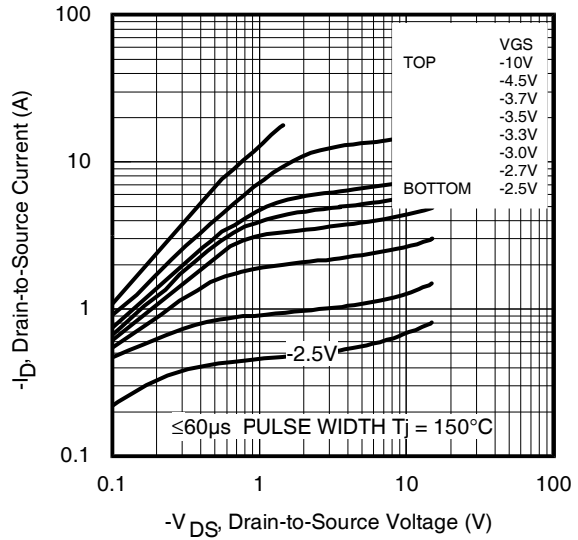


Fig 2. Typical Output Characteristics

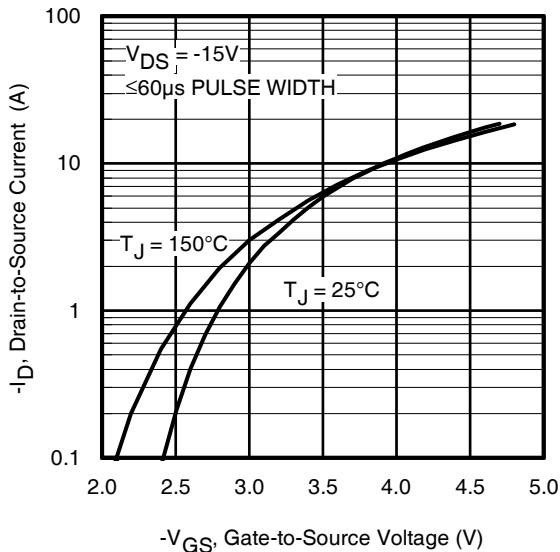


Fig 3. Typical Transfer Characteristics

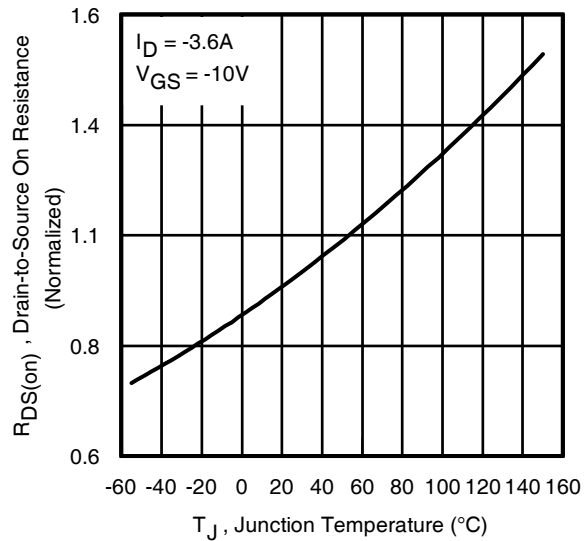


Fig 4. Normalized On-Resistance Vs. Temperature

LOW VOLTAGE MOSFET (P-CHANNEL)

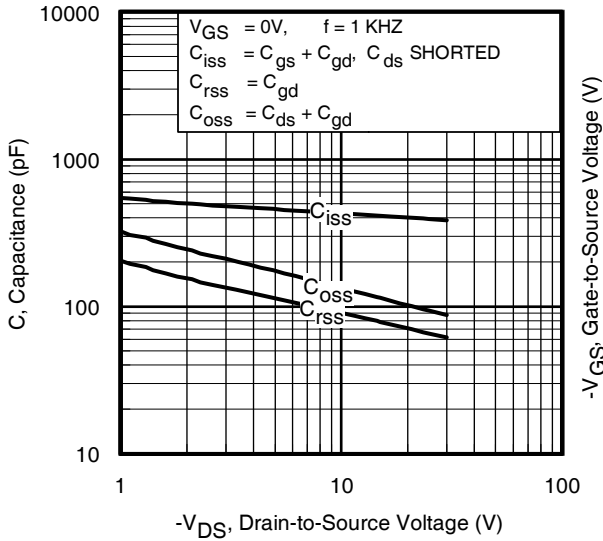


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

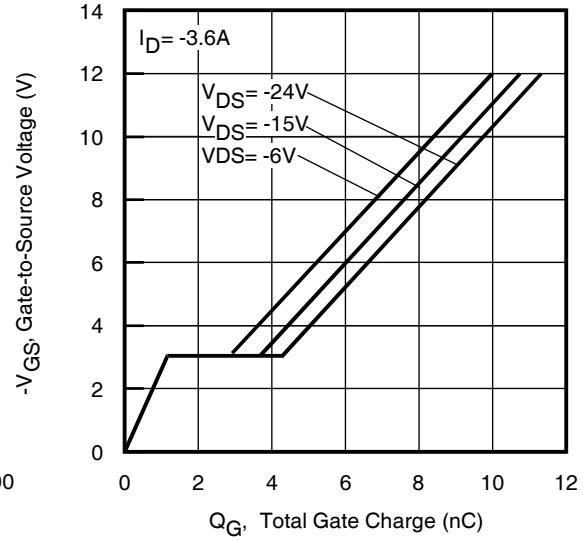


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

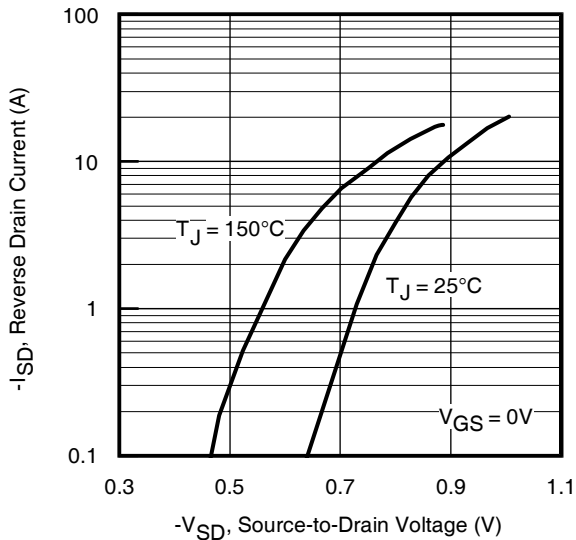


Fig 7. Typical Source-Drain Diode Forward Voltage

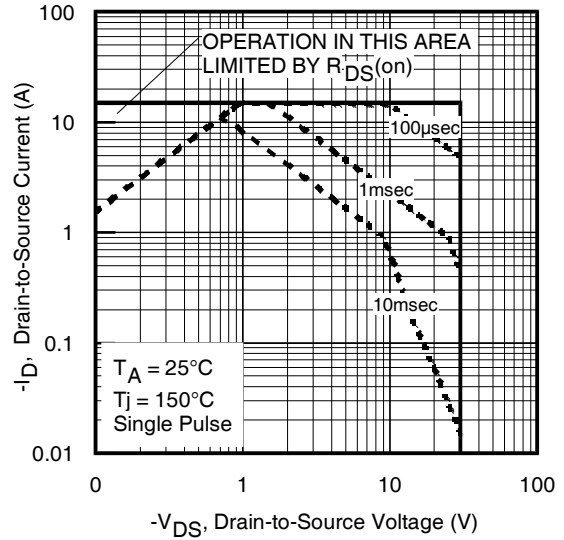


Fig 8. Maximum Safe Operating Area

LOW VOLTAGE MOSFET (P-CHANNEL)

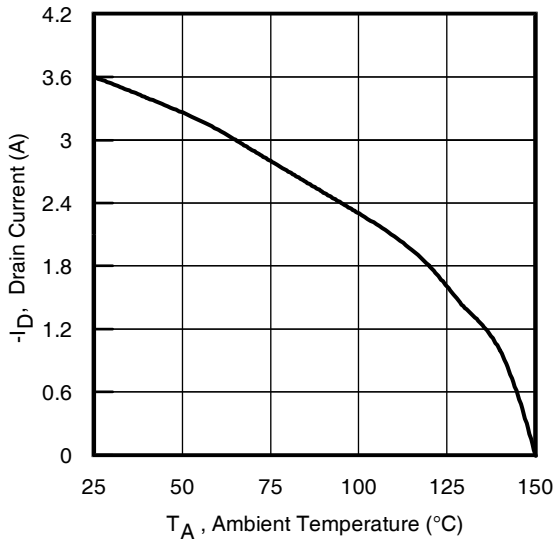


Fig 9. Maximum Drain Current Vs. Ambient Temperature

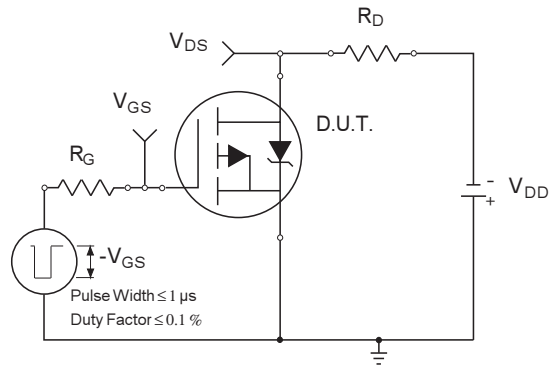


Fig 10a. Switching Time Test Circuit

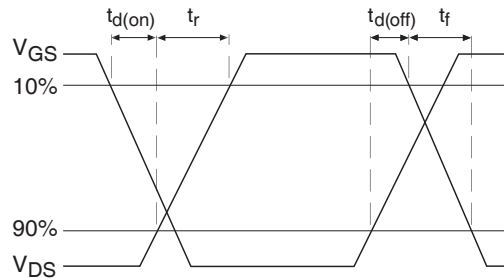


Fig 10b. Switching Time Waveforms

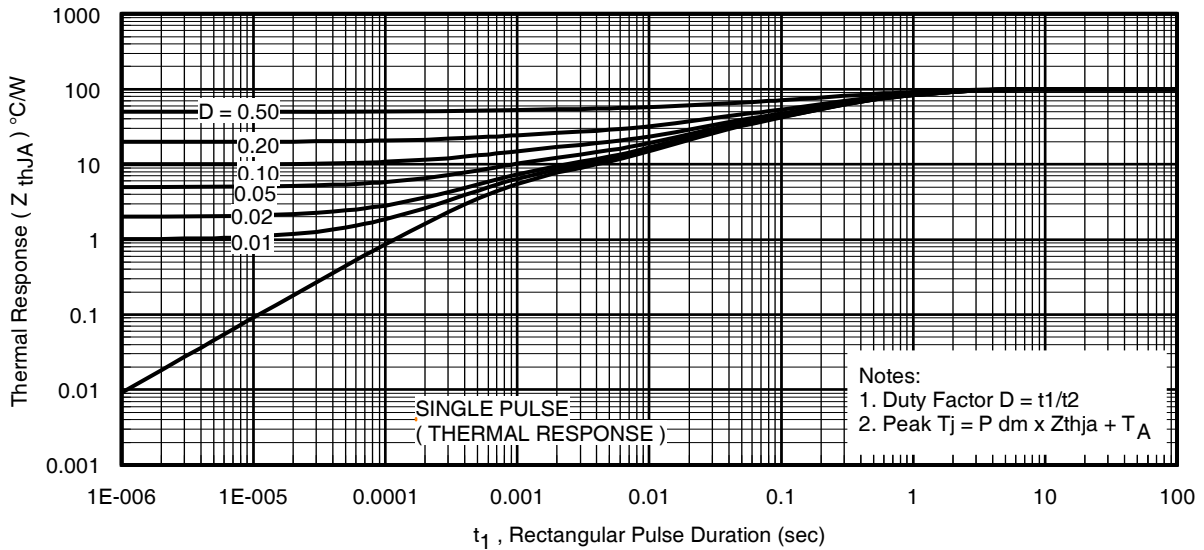


Fig 11. Typical Effective Transient Thermal Impedance, Junction-to-Ambient

LOW VOLTAGE MOSFET (P-CHANNEL)

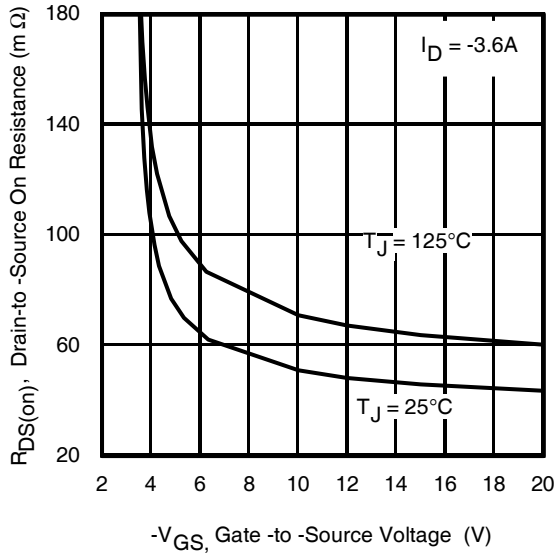


Fig 12. Typical On-Resistance Vs. Gate Voltage

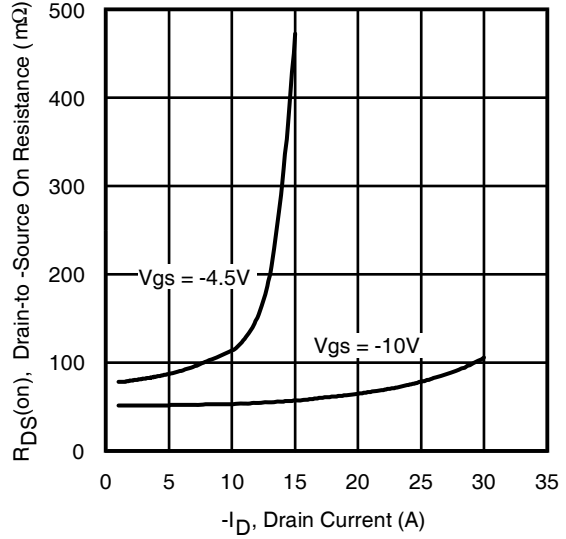


Fig 13. Typical On-Resistance Vs. Drain Current

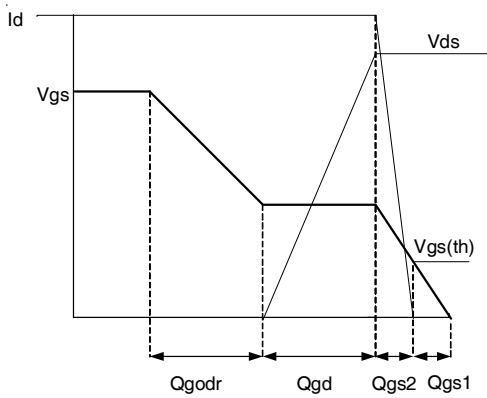


Fig 14a. Gate Charge Waveform

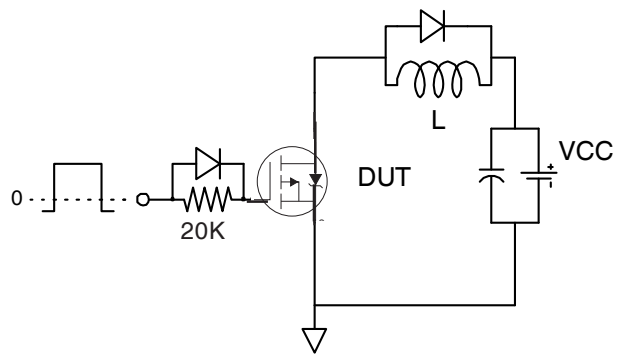


Fig 14b. Gate Charge Test Circuit

LOW VOLTAGE MOSFET (P-CHANNEL)

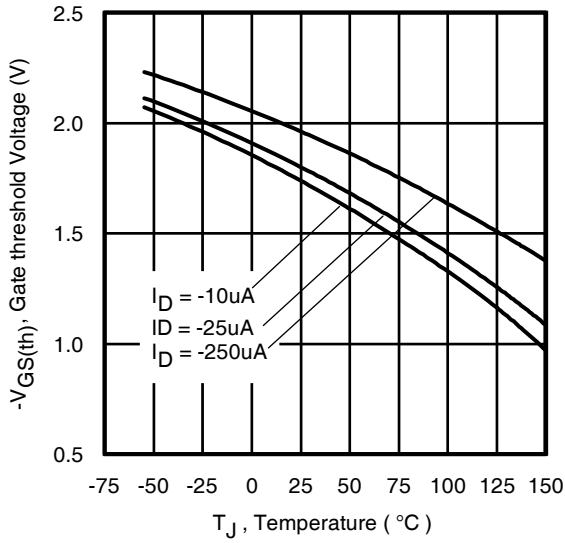


Fig 15. Typical Threshold Voltage Vs. Junction Temperature

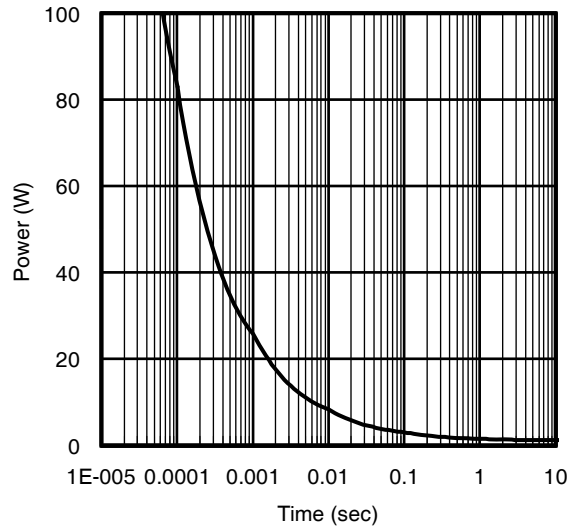
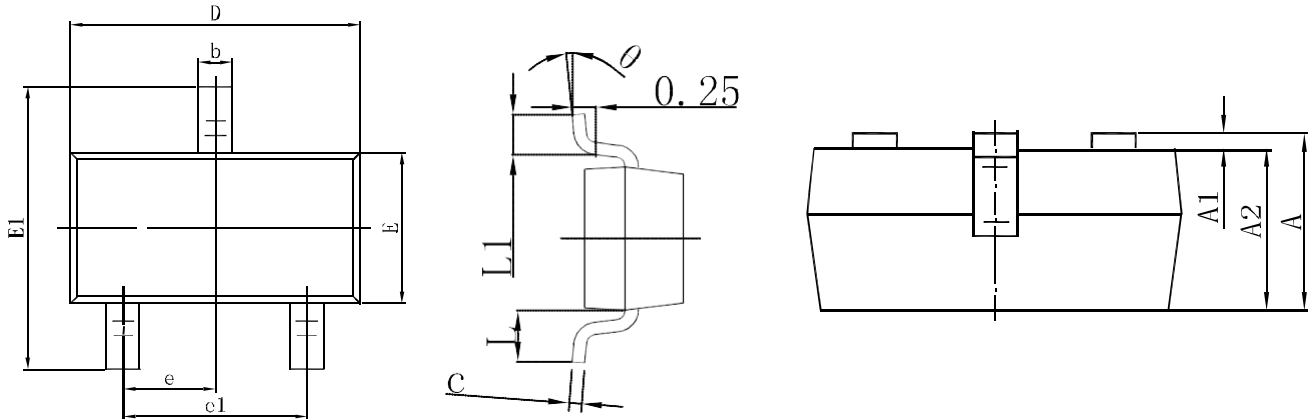


Fig 16. Typical Power Vs. Time

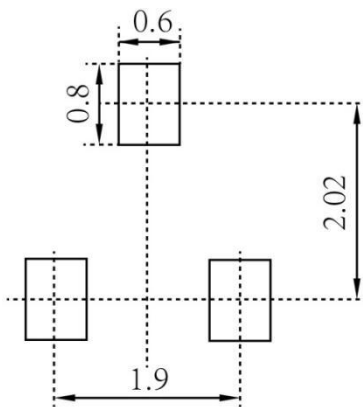
LOW VOLTAGE MOSFET (P-CHANNEL)

SOT-23 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

SOT-23 Suggested Pad Layout



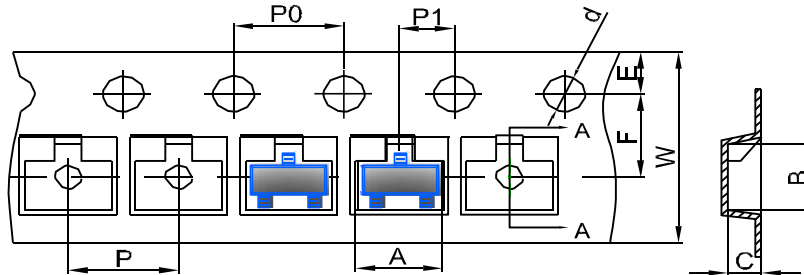
Note:

1. Controlling dimension: in millimeters
2. General tolerance: $\pm 0.05\text{mm}$
3. The pad layout is for reference purposes only

LOW VOLTAGE MOSFET (P-CHANNEL)

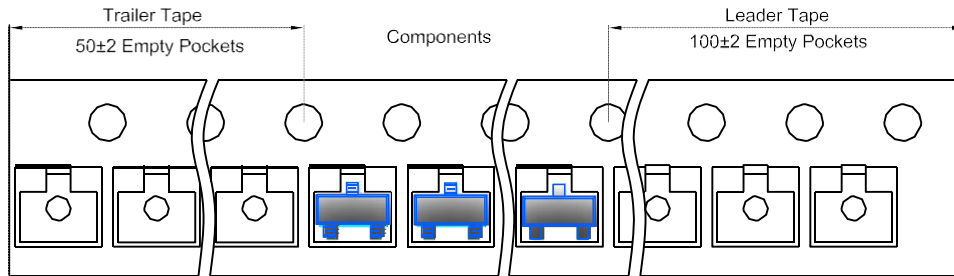
SOT-23 Tape and Reel

SOT-23 Embossed Carrier Tape

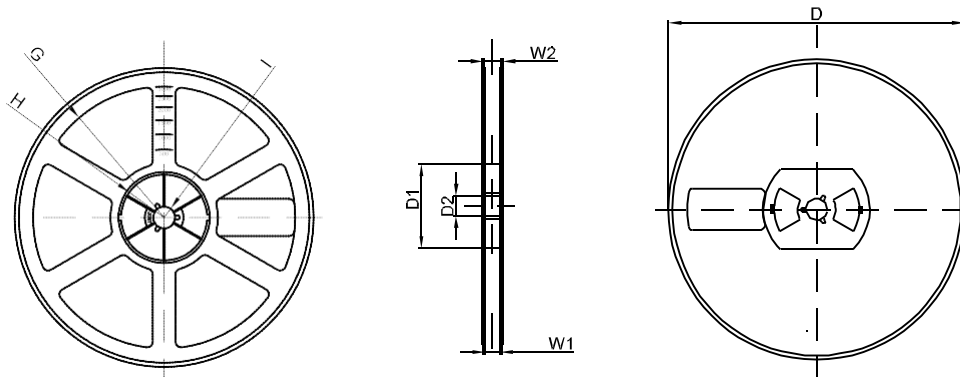


DIMENSIONS ARE IN MILLIMETER										
TYPE	A	B	C	d	E	F	P0	P	P1	W
SOT-23	3.15	2.77	1.22	Ø1.50	1.75	3.50	4.00	4.00	2.00	8.00
TOLERANCE	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1

SOT-23 Tape Leader and Trailer



SOT-23 Reel



DIMENSIONS ARE IN MILLIMETER								
REEL OPTION	D	D1	D2	G	H	I	W1	W2
7" DIA	Ø178	54.40	13.00	R78	R25.60	R6.50	9.50	12.30
TOLERANCE	±2	±1	±1	±1	±1	±1	±1	±1